



PRODUCT DATASHEET



- PLCC2 Side View
- ▶ 0.6T (3.8x1.2x0.6mm)
- Cool White

Release Date: 13 November 2015 Version: A1.2

N0W01S85SV





APPLICATIONS:

- Backlighting
- Indication Light
- Side view light strip
- Switch light

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Side View 0.6T



FEATURES:

- Package: Side View PLCC White SMT Package
- Forward Current: 20mA
- Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 1500mcd @20mA
- Colour: Cool White
- Colour Temperature: 6700-9800K
- Viewing angle: 110°
- Materials:
 - Die: InGaN/GaN
 - Resin: Epoxy (Yellow Diffused)
- **Operating Temperature:** -20~+80°C
- Storage Temperature: -30~+100°C
- **ESD:** 500V
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Chromaticity Coordinates
- Soldering methods: IR reflow
- **Preconditioning:** acc. to JEDEC Level 3
- Packing: 12mm tape with 3000/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

| Parameter | Symbol | Ratings | Unit |
|--------------------------------------|------------------|----------|------|
| Forward Current | I _F | 30 | mA |
| Peak Forward Current Duty 1/10@10KHz | I _{FP} | 100 | mA |
| Reverse Current @5V | I _R | 50 | μΑ |
| Power Dissipation | PD | 120 | mW |
| Electrostatic Discharge | ESD | 500 | V |
| Operating Temperature | T _{OPR} | -20~+80 | °C |
| Storage Temperature | T _{STG} | -30~+100 | °C |

Electrical & Optical Characteristics (Ta=25°C)

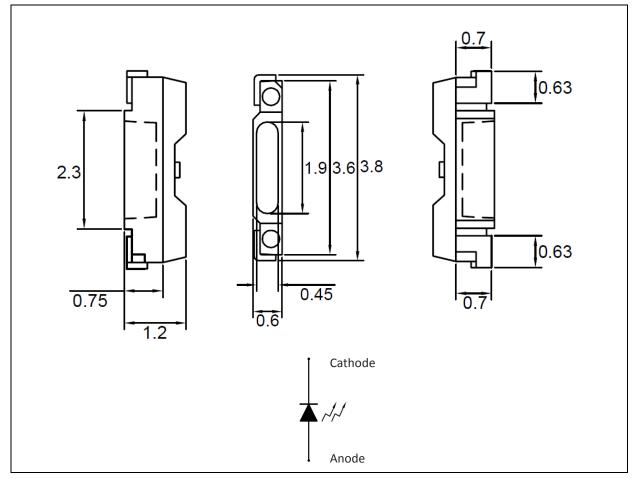
| Parameter | Symbol | Values | | | Unit | Test | |
|--------------------|-------------------|--------|------|-------|------|----------------------|--|
| Farameter | Symbol | Min. | Тур. | Max. | Onit | Condition | |
| Forward Voltage | V _F | 2.8 | | 3.4 | V | I _F =20mA | |
| Luminous Intensity | Iv | 1200 | 1500 | | mcd | I _F =20mA | |
| Chromaticity | х | 0.287 | | 0.311 | | L 20m A | |
| Coordinates | Y | 0.276 | | 0.315 | | I _F =20mA | |
| Viewing Angle | 20 _{1/2} | | 110 | | deg | I _F =20mA | |

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V



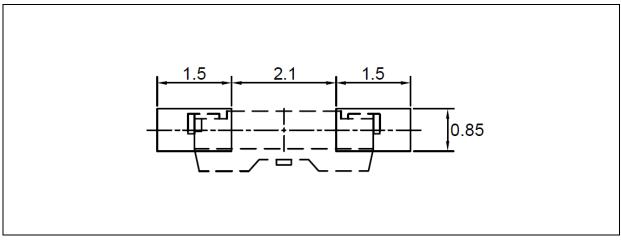
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



BINNING GROUPS:

| Code | Min. | Max. | Unit |
|------|------|------|------|
| 1 | 2.8 | 2.9 | |
| 2 | 2.9 | 3.0 | |
| 3 | 3.0 | 3.1 | V |
| 4 | 3.1 | 3.2 | v |
| 5 | 3.2 | 3.3 | |
| 6 | 3.3 | 3.4 | |

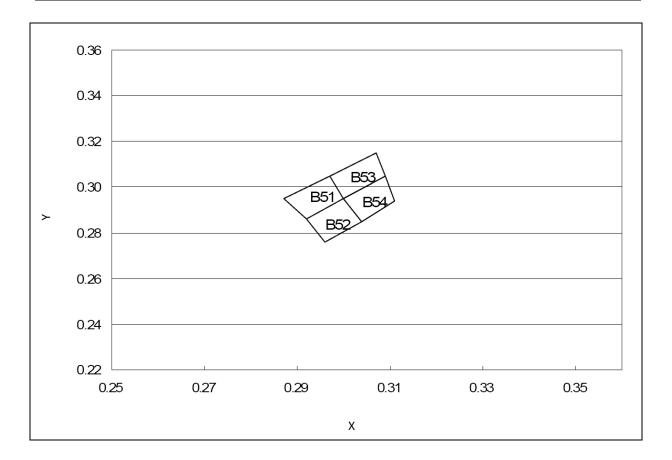
Forward Voltage Classifications ($I_F = 20mA$):

Luminous Intensity Classifications (I_F = 20mA):

| Code | Min. | Max. | Unit |
|------|------|------|------|
| | | | Onit |
| W12 | 1200 | 1250 | |
| W13 | 1250 | 1300 | |
| W14 | 1300 | 1350 | |
| W15 | 1350 | 1400 | |
| W21 | 1400 | 1450 | |
| W22 | 1450 | 1500 | mad |
| W23 | 1500 | 1550 | mcd |
| W24 | 1550 | 1600 | |
| W25 | 1600 | 1650 | |
| W31 | 1650 | 1700 | |
| W32 | 1700 | 1750 | |
| W33 | 1750 | 1800 | |



CIE CHROMATICITY DIAGRAM:

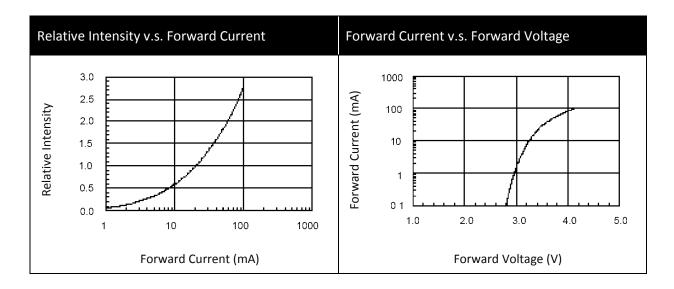


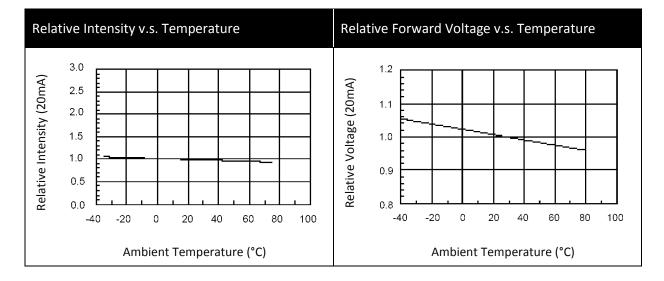
Chromaticity Coordinates Classifications (I_F = 20mA):

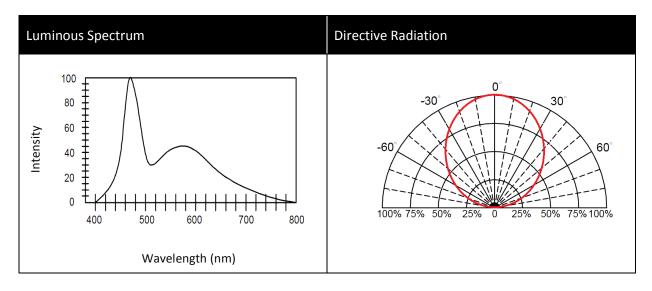
| | 1 | L | 2 | | 3 | | 4 | |
|-----|--------|--------|--------|--------|--------|--------|--------|--------|
| | Х | Y | Х | Y | Х | Y | Х | Y |
| B51 | 0.2870 | 0.2950 | 0.2920 | 0.2860 | 0.3000 | 0.2950 | 0.2970 | 0.3050 |
| B52 | 0.2920 | 0.2860 | 0.2960 | 0.2760 | 0.3040 | 0.2850 | 0.3000 | 0.2950 |
| B53 | 0.2970 | 0.3050 | 0.3000 | 0.2950 | 0.3090 | 0.3050 | 0.3070 | 0.3150 |
| B54 | 0.3000 | 0.2950 | 0.3040 | 0.2850 | 0.3110 | 0.2940 | 0.3090 | 0.3050 |



ELECTRO-OPTICAL CHARACTERISTICS:



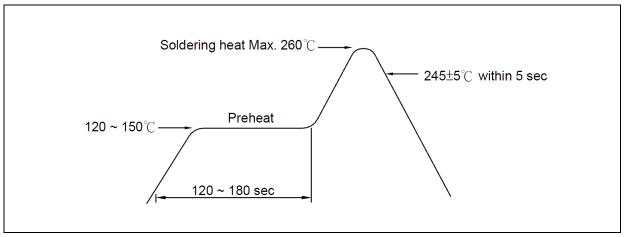




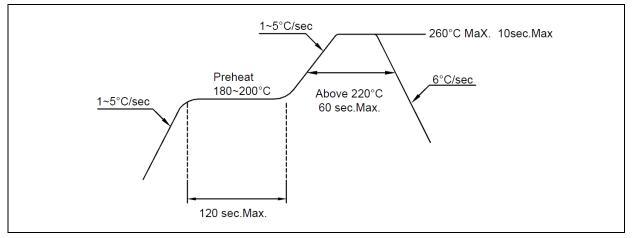


RECOMMENDED SOLDERING PROFILE:

Wave Solder:



Lead-free Solder:



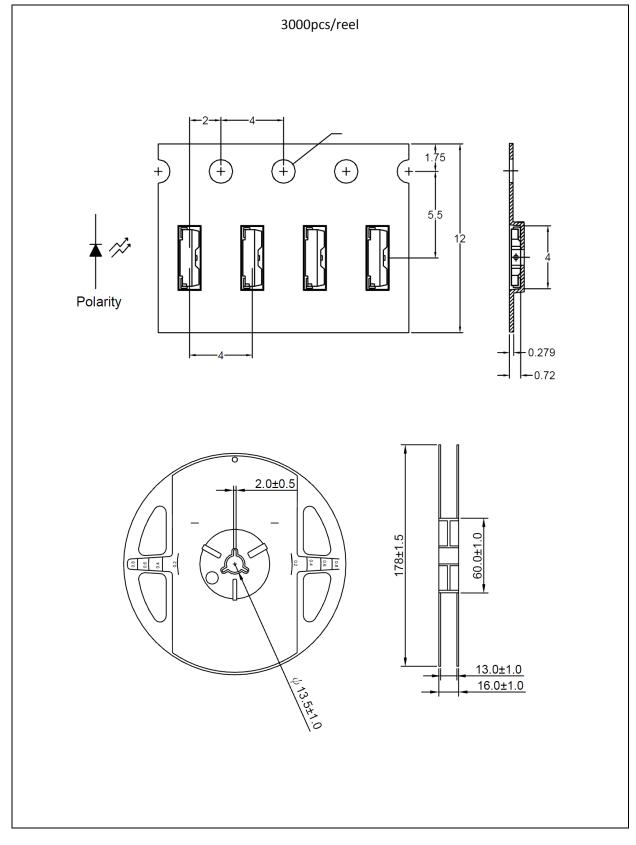
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

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Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

| Version | Date | Summary of Revision |
|---------|------------|-------------------------------------|
| A1.0 | 20/12/2013 | Datasheet set-up. |
| A1.1 | 17/10/2014 | Update series name. |
| A1.2 | 13/11/2015 | Part number adds -SV for side view. |

